TechARENA 1

Packaging Exhibitor Presentations

Time: 10:15 - 11:30

10:15 Large-field stepper and a full-field projection aligner for 2.5D/3D packaging, MEMS, and Power devices
Fumi Nakazawa, Sales Representative, USHIO

10:30 Flexible, Cost Effective PVD Solution for Advanced Packaging 3D/WLP Applications
Glyn Reynolds, Principal Scientist R&D, Oerlikon

10:45 Packaging in Europe - Advances in System Integration on Wafer Level
Steffen Kröhnert, Director of Technology, NANIUM S.A.

11:00 Innovative resist processing for advanced packaging
Anton Pecic, Business Development Manager, EV Group

11:15 European bespoke wafer processing and development solutions for grinding, CMP, Edge Treatment, Wafer Bonding, Dicing and cleaning
Georges Puyre, Sales and Marketing Director, Rockwood Wafer Reclaim

Plastic Electronics Exhibitor Presentation

Time: 11:45 - 12:30

11:45 Lab-to-Fab Micro Contact Printing for Flexible Electronics
Gerald Krenzki, Product Manager, EV Group

MEMS Exhibitor Presentations

Time: 12:45 - 13:45

12:45 Exhaust Gas treatment with focus on dry bed absorption for Semiconductor, Photovoltaics and MEMS Industries and R&D applications
Peter Kaiser, Sales Manager D-A-CH, CS Clean Systems

13:00 Micro- and Nanofabrication at DTU Danchip, Denmark
Jörg Hübner, Director, DTU Danchip

13:15 MEMS Design: Verifying resonance frequencies to match design objectives
Edward Chyau, Sales Director, ARDIC Instruments

13:30 PVD high volume production solution for deposition of PZT thin films
Glyn Reynolds, Principal Scientist, Oerlikon Systems

Secondary Equipment Session & Exhibitor Presentations

Time: 14:00 - 17:10

14:00 Welcome
Martin Heerschop, Sales Director, Solutions on Silicon

14:10 Human performances deployment within high tech tool environment
Peter Gaboury, Senior Program Manager, STMicroelectronics

14:30 Automotive Semiconductor and Sensor Manufacturing in Europe
Thorsten Widmer, Director Waferfab, Bosch

14:50 Joint development topics for semiconductor manufacturers and their suppliers in Germany
Martin Schellenberger, Teamleader, Fraunhofer IISB

15:10 New Controller for Applied Materials 200mm Systems
Joerg Recklies, Director Maintenance Engineering, Infineon

15:30 System enhancement by replacing the heart of the production equipment
Frank Geissler, Head of Sales Control Systems / SI, Semi / PV, AIS Automation GmbH

15:45 Panel discussion: Customer Success Criteria for 200mm Manufacturing in Europe

Exhibitor Presentations

16:10 AIESEC – World’s largest student organization
Nicolas Mesa, Vice President Finance, AIESEC

16:25 Lam Research

16:40 ASML

Tuesday 8 October

Emerging Research Materials - Session 1

Time: 10:30 - 12:45

10:30 Welcome
Mart Graef, Strategic Program Manager, TU Delft

10:40 Wafer-scale fabrication of graphene
Sten Voelblet, Delft University of Technology

11:05 Graphene - Opportunities and challenges
Richard van Rijn, CTO, Applied Nanolayers

11:30 The Graphene Flagship – Working together to transform scientific excellence to societal impacts
Jari Kinaret, Professor, Chalmers University of Technology

11:55 Graphene in Flexible Electronics
Tapani Ryhätan, Director, Head of Sensor and Material Technologies Laboratory, Nokia

12:20 Integrated Graphene Devices
Max Lemme, Professor, KTH Royal Institute of Technology

Emerging Research Materials - Session 2

Time: 14:00 - 16:55

New Trends in Epitaxy and Atomic Layer Processing

14:00 Welcome
Johann Bartha, Professor, Technical University Dresden

14:10 Epitaxy of SiGe and III-nitrides as a key enabler in advanced nanoelectronics and optoelectronics
Jean Michel Hartmann, CEA Senior Expert, CEA Leti

14:35 Enabling solutions for selective epitaxial growth of Si based alloys (SiCP, Si:P, Si:C, i-Si)
Sundeep Mehta, Director of epitaxial process & applications development, ASM

15:00 Automated ALD precursor qualification
Johann Bartha, Professor, Technical University Dresden

15:25 Spatial Atomic Layer Deposition; a novel disruptive technology
Fred Roozeboom, Professor, TNO

15:50 ECD superfill by surfactant competition
Romy Liske, Group Leader Interconnects, Fraunhofer IPMS

16:15 Analysis of ultrathin films in state-of-the-art CMOS devices
Susanne Ohsiek, Principal Engineer Complex Analysis, GLOBALFOUNDRIES

16:40 Reconfigurable Si-Nanowire Devices
André Heinzig, NuMuLab
**TechARENA 1**

**Market Briefing**
- **10:30** Global Semiconductor market update  
  Clark Tseng, Senior Manager Market Analysis, SEMI Taiwan
- **11:00** More Than Moore markets in Europe  
  Jean-Christophe Eloy, President and CEO, YOLE Développement
- **11:30** 10/100/20: Update on Europe’s New Semiconductor Strategy  
  Ourania Georgoutsakou, Director Public Policy, SEMI Europe
- **12:00** HR challenges in the semiconductor industry  
  Andreas C. Zimmer, Founder, ZianCo

**Test Exhibitor Presentations**
- **12:45** NEW Wafer Handling Robot for High Vacuum Applications  
  Andreas Maas, Project Manager, Adenso
- **13:00** Building Analog Self-Test into Crowded SoCs  
  Ian Stevenson, Commercial Manager, Ateeda
- **13:15** An introduction to cloud test, making chip test available for everyone  
  Manabu Kimura, President, Cloud Testing Services

**Best of Advanced Process Control**
- **14:00** Welcome  
  Michael Klick, Plasmetrex
- **14:05** Ultrafast and high sensitive sensors for lifetime topography on Si-wafers  
  Kay Dornich, CEO, Freiberg Instruments GmbH
- **14:35** Robust and Interpretable Multivariate Process Control of Temporal Wafer Data  
  Peter Scheibelhofer, Freelance contractor, AMS
- **15:05** Integration between FDC and Dispatcher systems to improve manufacturing key parameters  
  Natalina Di Stefano, Senior Process Control Engineer, STMicroelectronics

**Night of Knowledge**
- **16:00** Welcome  
  Michael Klick, Plasmetrex
- **14:05** Future microelectronics applications and their impact on semiconductor manufacturing.  
  Stephan Raithel, SEMI Europe
- **14:05** ITRS update  
  Mart Graef, TU Delft
- **14:15** Challenges for a material supplier to cope with new IC technology trends  
  Jonas Jeanaeau, Applications Manager, Brewer Science
- **14:20** Semiconductor technology enabling smart electronics  
  Lode Lauwers, Vice President, imec
- **14:40** Thin Wafer Handling Debonding Mechanisms  
  Jonathan Jeanaeau, Applications Manager, Brewer Science
- **19:00** Networking Reception with visit of demo stations:  
  ST Microelectronics, NXP, imec, and Bosch

**SEMICON Europa 2013**

**Wednesday**

**9 October**

**Silicon Photonics Session**
- **10:30** Interconnecting at light speed  
  Richard Fournel, Director of Mixed Process Technology Line, STMicroelectronics
- **10:40** KEYNOTE: Silicon Photonics for the Zettabyte Era  
  Marco Romagnoli, Head of Advanced Technologies for Photonic Integration, CNIT
- **11:10** Packaging and integration technologies for silicon photonics  
  Peter O’Brien, Head of the Photonics Packaging Research Group, Tyndall
- **11:30** Integrated electro-optical waveguide based devices with liquid crystals on a silicon Backplane  
  Florenta Costache, Group Manager Smart Micro-Optics SMO / AMS, Fraunhofer Institute for Photonic Microsystems
- **12:00** Silicon Photonics for Efficient Data Communications: ST advantage and solution  
  Maurizio Zuffada, Mixed Process Division Advanced R&D Director, STMicroelectronics

**3D TSV Session:**
- **13:45** The best of European 3D TSV Summit 2013  
  Didier Louis, International Communication Manager, CEA-Leti
- **13:50** 3DIC market trends and technological evolutions  
  Rozalia Beica, CTO, Yole
- **14:15** On the Road to 3D IC: Markets and Solutions  
  Jan Vardaman, President, TechSearch
- **14:40** 3D Technologies for More Efficient Product Development  
  Hervé Ribot, 3D Session Manager, CEA Leti
- **15:05** Fraunhofer 3D Cluster – Competence and Know How for 3D Systems  
  Jürgen Wolf, Head of Dept. Wafer Level System Integration, Management ASSID, Fraunhofer IZM-ASSID
- **15:30** MEMS Fusion – Challenges and Chances in Final Test  
  James Quinn, Vice President Sales and Marketing, Multitest
- **15:55** European 3D TSV Summit 2014 – Application Ready  
  Yann Guillou, Business Development & EU Standard Manager, Europe Grenoble Office

**Exhibitor Presentations**
- **16:20** Status Interposer Technology at IZM-ASSID  
  Mathias Böttcher, Fraunhofer IZM-ASSID
- **16:35** Era of 3DIC Solutions for Bubble Free Bonding, Wafer Handling and Thin Wafer Shipping in Full Automatic Controlled Environment Mode  
  Jorgen Lundgren, Senior Field Applications Engineer Microenvironments, Entegris
- **16:50** 3D technologies for integration of MEMS and Electronics  
  Lutz Hofmann, Back End of Line, Fraunhofer ENAS and Center for Microtechnologies/TU Chemnitz

Program is subject to change.
# TechARENA 1

**Next Generation Lithography Session**

<table>
<thead>
<tr>
<th>Time</th>
<th>Session Title</th>
<th>Speaker(s)</th>
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</thead>
<tbody>
<tr>
<td>10:15</td>
<td>Welcome</td>
<td>Kurt Ronse, Lithography Department Director, imec</td>
</tr>
<tr>
<td>10:20</td>
<td>Status and Challenges of EUV Lithography</td>
<td>Jan-Willem van der Horst, Product Manager EUV, ASML</td>
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<td>10:40</td>
<td>High NA - the extension path of EUV Lithography</td>
<td>Reiner Garreis, Senior Director System Engineering, Zeiss SMT</td>
</tr>
<tr>
<td>11:00</td>
<td>Status and Challenges of directed Self-Assembly</td>
<td>Roel Gronheid, Principal Scientist, imec</td>
</tr>
<tr>
<td>11:20</td>
<td>Status and Challenges for Probe Nanopatterning</td>
<td>Urs Duering, Manager Nanofabrication, IBM Research - Zurich</td>
</tr>
<tr>
<td>11:40</td>
<td>Status and Challenges for EUV mask manufacturing</td>
<td>Christian Bourgel, Senior Member of Technical Staff, AMTC</td>
</tr>
<tr>
<td>12:00</td>
<td>Electron multi-beam mask writer (MBMW) for the 11nm HP technology node and below</td>
<td>Elmar Platzgummer, CEO, IMS Nanofabrication</td>
</tr>
<tr>
<td>12:20</td>
<td>Status and Challenges for Multi-beam E-beam for direct write</td>
<td>Delphine Marris-Morini, Assistant Professor, CEA-Leti</td>
</tr>
<tr>
<td>12:40</td>
<td>TSub-Wavelength Holographic Lithography (SWHL) as an Alternative to DUVL</td>
<td>Vadim Rakhovsky, CEO and Founder, NANOTECH SWHL</td>
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# TechARENA 2

**Workshop on Equipment Assessment & Equipment Performance Improvements**

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<tr>
<th>Time</th>
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<th>Speaker(s)</th>
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</thead>
<tbody>
<tr>
<td>10:15</td>
<td>Welcome</td>
<td>Markus Pfeffer, Group Manager, Fraunhofer IISB</td>
</tr>
<tr>
<td>10:20</td>
<td>Nanotopography Measurement of Non-Polished Wafers</td>
<td>Stefan Bauer, Manager Metrology, Siltronic AG</td>
</tr>
<tr>
<td>10:40</td>
<td>SWAT – A new CU WET Etch Approach</td>
<td>Stephan Henneck, Unit Process Development - WET, Infineon</td>
</tr>
<tr>
<td>11:00</td>
<td>Joint Assessment of Novel Multi Column eBeam Inspection System</td>
<td>Ido Holcman, Head of eBeam System &amp; Technology / Product Development Division / PDC, Applied Materials</td>
</tr>
<tr>
<td>11:20</td>
<td>Metrology, Process Control, Automation and Software &amp; Exhibitor Presentations</td>
<td>Shay Reboh, CEA - Leti</td>
</tr>
<tr>
<td>11:40</td>
<td>Welcome</td>
<td>Michael Arnold, Managing Director, PEER Group</td>
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<tr>
<td>11:45</td>
<td>A Predictive Carrier Logistics Roadmap</td>
<td>Jan Rothe, Equipment Management Global Domain Team, GLOBALFOUNDRIES</td>
</tr>
<tr>
<td>12:05</td>
<td>Integrated Experiment Management for Semiconductor Fab Automation</td>
<td>Kerstin Kurfürst, Senior Staff engineer IT, Infineon</td>
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<tr>
<td>12:25</td>
<td>Fault Detection and Data Analysis in TI’s Freising Litho Area</td>
<td>Gernot Biese, Process Engineer Photolithography, Texas Instruments</td>
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<tr>
<td>12:55</td>
<td>Novel Slurry Injection System for Reduced Slurry Usage and Enhanced CMP Performance</td>
<td>Ara Philipposian, President and CEO, Araca</td>
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<tr>
<td>13:10</td>
<td>Information Integration: A Key For Successful Process Control</td>
<td>Hans Mayer, COO, znt Zentren für Neue Technologien</td>
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<tr>
<td>13:25</td>
<td>Open-heart surgery – IT consolidation and migrating in full operation</td>
<td>Christoph Nicolaus, Manager Corporate Communications, Systema</td>
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<tr>
<td>13:40</td>
<td>Introduction of Novel 3D Metrology Tool for Leading Edge Devices</td>
<td>Kazuhiro Arai, Product Development Manager, Advantest</td>
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<tr>
<td>13:55</td>
<td>Cleanroom Suitable Assessment of Equipment according to upcoming ISO standards</td>
<td>Frank Bürger, Key Account Manager Certification, Fraunhofer IPA</td>
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<tr>
<td>14:10</td>
<td>SCOUT – a new autonomous &amp; flexible transport system for the use in cleanrooms</td>
<td>Karl Hantschsmann, Division Manager Automation, Roth &amp; Rau - Ortner</td>
</tr>
<tr>
<td>14:25</td>
<td>Enhancing legacy MES by a truly modular state-of-the-art MOM solution</td>
<td>Tom Bednarz, Managing Director, Critical Manufacturing Deutschland</td>
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